



STS12NF30L

N-channel 30 V, 0.008 Ω , 12 A STripFET™ II Power MOSFET in SO-8 package

Datasheet — production data

Features

Order code	V _{DSS}	R _{DS(on)}	I _D
STS12NF30L	30 V	< 0.009 Ω	12 A

- Standard outline for easy automated surface mount assembly
- Low threshold drive

Applications

- Switching application

Description

This Power MOSFET has been developed using STMicroelectronics' unique STripFET process, which is specifically designed to minimize input capacitance and gate charge. This renders the device suitable for use as primary switch in advanced high-efficiency isolated DC-DC converters for telecom and computer applications, and applications with low gate charge driving requirements.

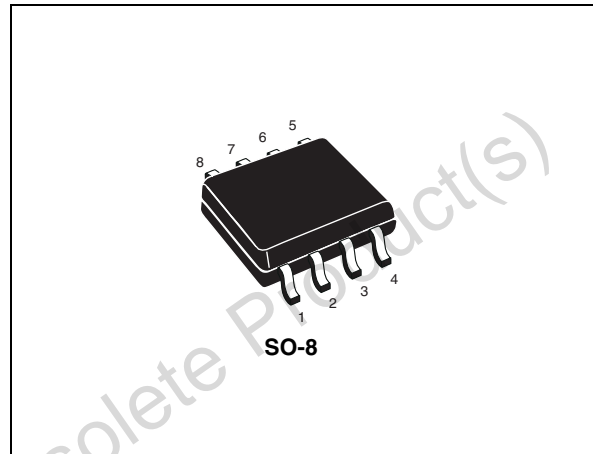


Figure 1. Internal schematic diagram

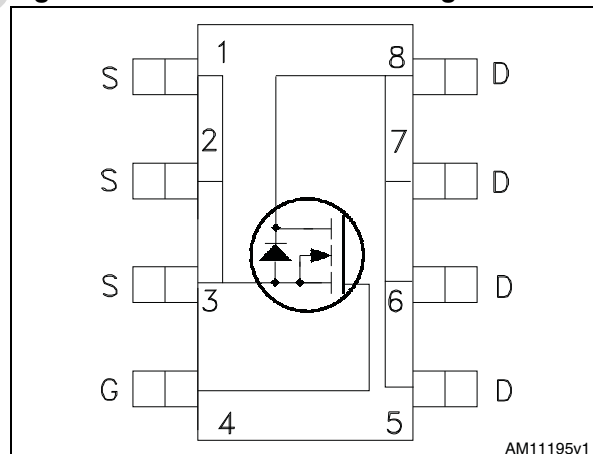


Table 1. Device summary

Order code	Marking	Package	Packaging
STS12NF30L	12F30L	SO-8	Tape and reel

Contents

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Obsolete Product(s) - Obsolete Product(s)

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	30	V
V_{GS}	Gate- source voltage	± 16	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	12	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	7.5	A
$I_{DM}^{(1)}$	Drain current (pulsed)	48	A
P_{TOT}	Total dissipation at $T_a = 25\text{ }^\circ\text{C}$	2.5	W
T_J	Maximum operating junction temperature	150	$^\circ\text{C}$
T_{stg}	Storage temperature	-55 to 150	$^\circ\text{C}$

1. Pulse width limited by safe operating area

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-a}^{(1)}$	Thermal resistance junction-ambient max	50	$^\circ\text{C/W}$

1. When mounted on FR-4 board of 1inch², 2oz Cu, $t < 10$ sec

2 Electrical characteristics

($T_{CASE} = 25\text{ °C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source Breakdown voltage	$I_D = 250\ \mu\text{A}$, $V_{GS} = 0$	30			V
I_{DSS}	Zero gate voltage Drain current ($V_{GS} = 0$)	$V_{DS} = 30\text{ V}$ $V_{DS} = 30\text{ V}$, $T_C = 125\text{ °C}$			1 10	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 16\text{ V}$			± 100	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$	1			V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$, $I_D = 6\text{ A}$ $V_{GS} = 4.5\text{ V}$, $I_D = 6\text{ A}$		0.008 0.01	0.009 0.011	Ω Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance			2400		pF
C_{oss}	Output capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0$	-	590		pF
C_{rss}	Reverse transfer capacitance			200		pF
Q_g	Total gate charge	$V_{DD} = 24\text{ V}$, $I_D = 12\text{ A}$, $V_{GS} = 4.5\text{ V}$ (see Figure 13)		35	50	nC
Q_{gs}	Gate-source charge		-	9		nC
Q_{gd}	Gate-drain charge			18		nC

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 15\text{ V}$, $I_D = 6\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (see Figure 12)	-	35	-	ns
t_r	Rise time			90		
$t_{d(off)}$	Turn-off-delay time	$V_{DD} = 24\text{ V}$, $I_D = 12\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (see Figure 14)	-	80	-	ns
t_f	Fall time			35		ns
$t_{r(Voff)}$	Off-voltage rise time	$V_{DD} = 24\text{ V}$, $I_D = 12\text{ A}$, $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (see Figure 14)	-	35	-	ns
t_f	fall time			35		ns
t_c	cross-over time			80		ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max	Unit
I_{SD}	Source-drain current		-		12	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		48	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 12\text{ A}, V_{GS} = 0$	-		1.3	V
t_{rr}	Reverse recovery time	$I_{SD} = 12\text{ A}, V_{DD} = 15\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s},$ $T_j = 150\text{ }^\circ\text{C}$ <i>(see Figure 14)</i>	-	114		ns
Q_{rr}	Reverse recovery charge			456		nC
I_{RRM}	Reverse recovery current			8		A

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

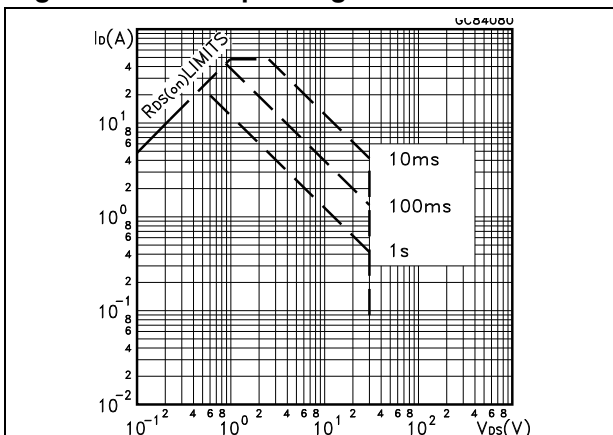


Figure 3. Thermal impedance

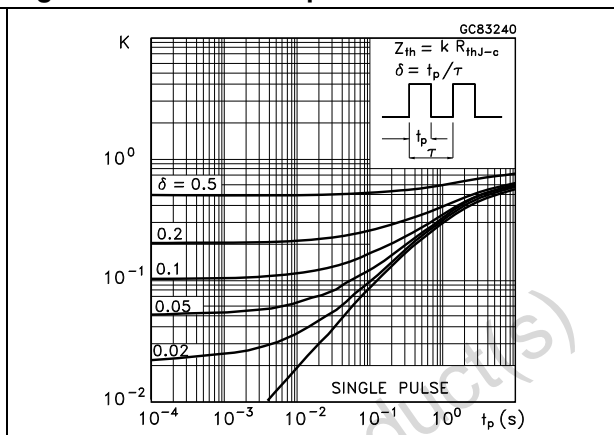


Figure 4. Output characteristics

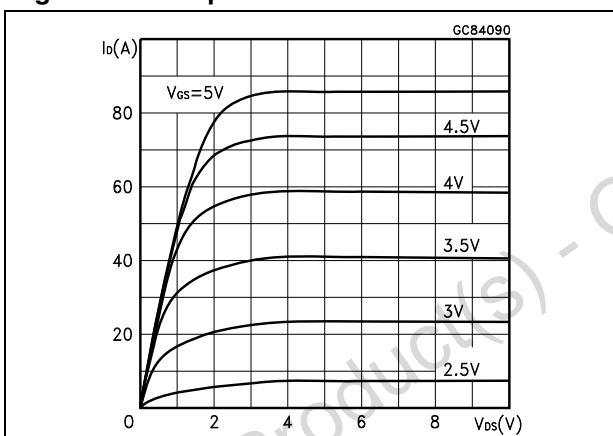


Figure 5. Transfer characteristics

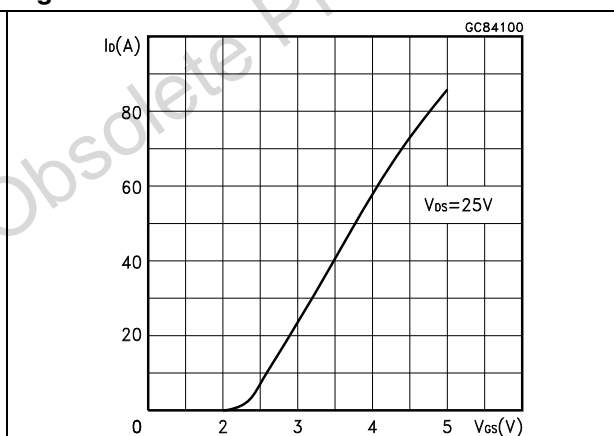


Figure 6. Source-drain diode forward characteristics

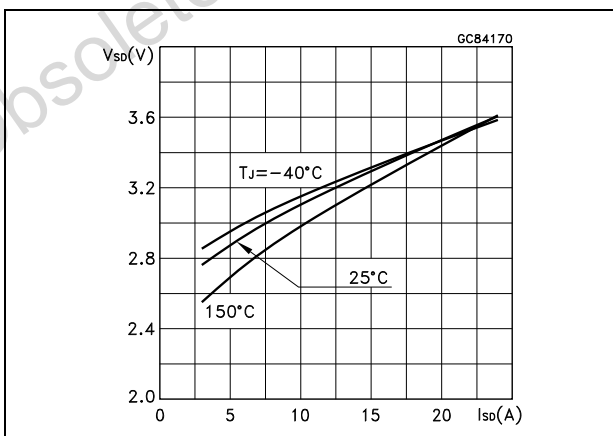


Figure 7. Static drain-source on resistance

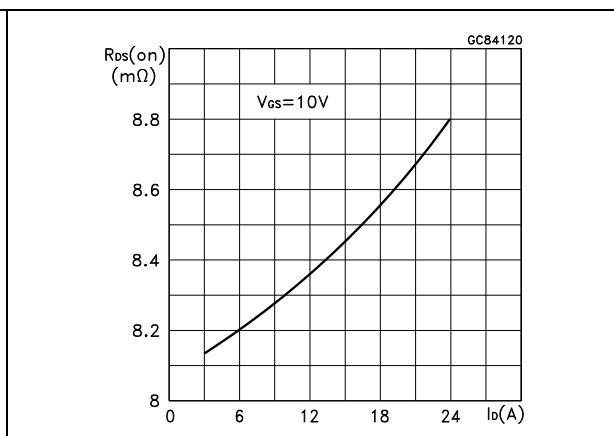


Figure 8. Gate charge vs. gate-source voltage

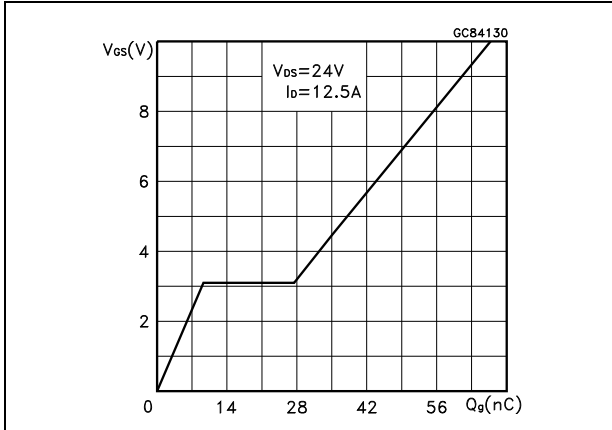


Figure 9. Capacitance variations

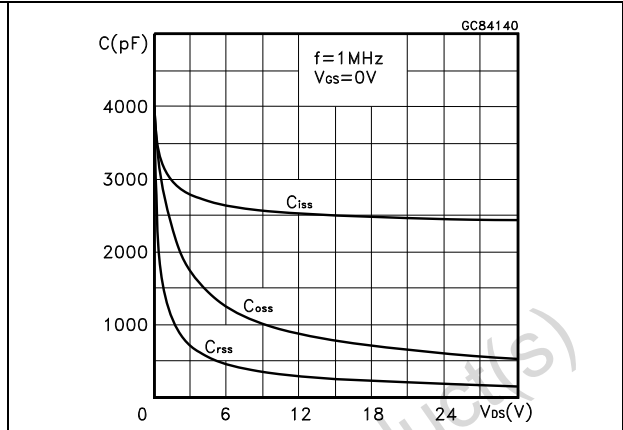


Figure 10. Normalized gate threshold voltage vs. temperature

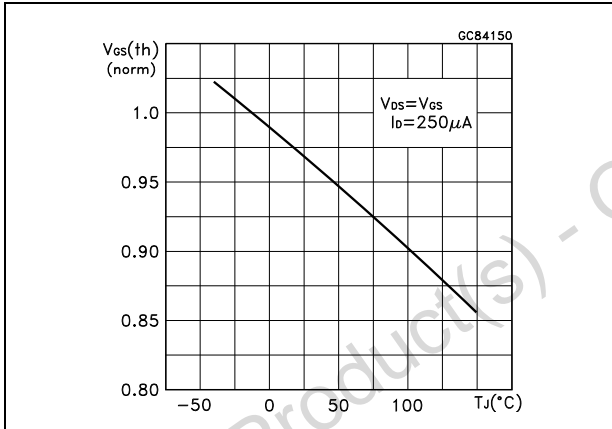
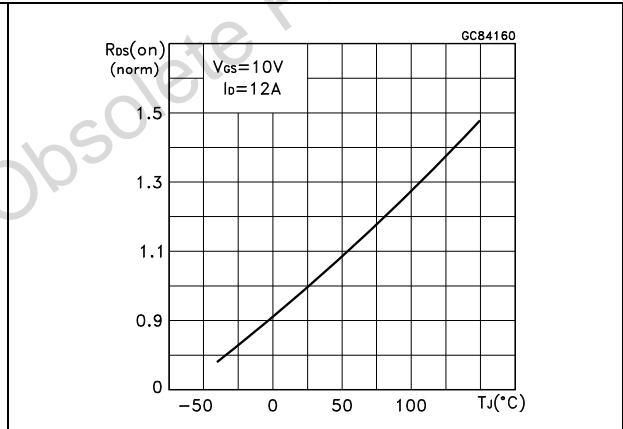


Figure 11. Normalized on-resistance vs. temperature



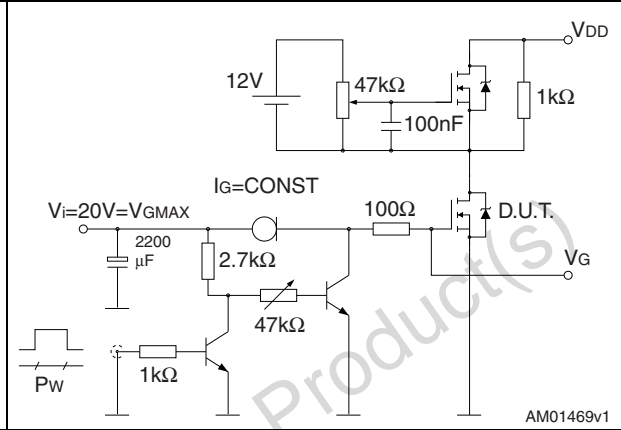
3 Test circuit

Figure 12. Switching times test circuit for resistive load



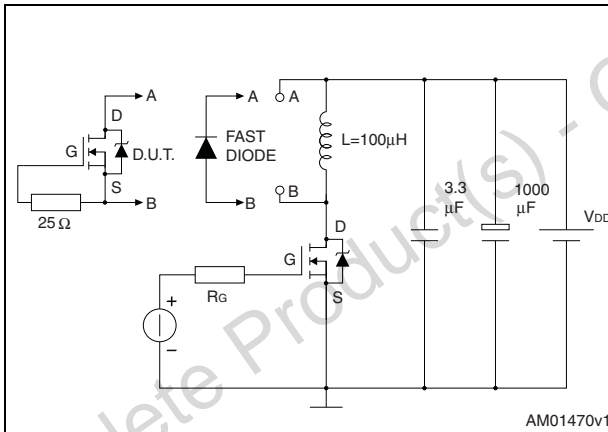
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Figure 13. Gate charge test circuit



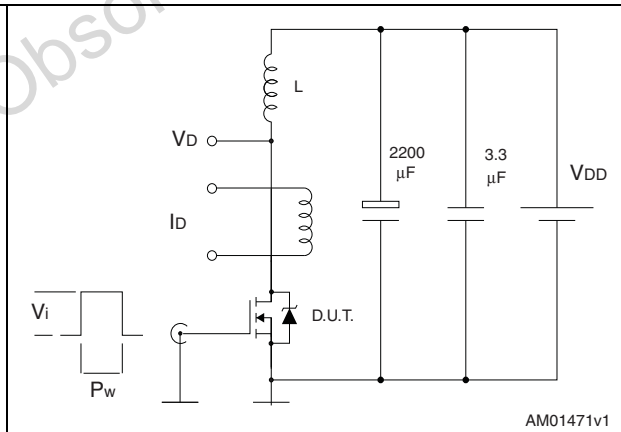
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Figure 14. Test circuit for inductive load switching and diode recovery times



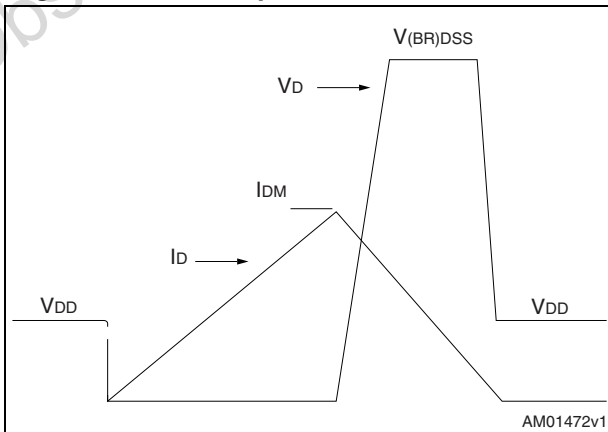
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Figure 15. Unclamped Inductive load test circuit



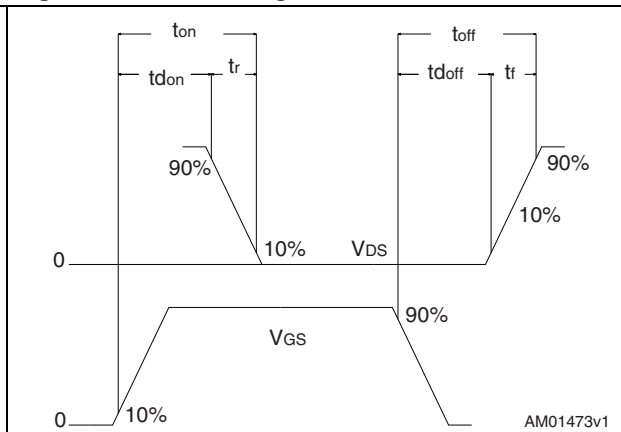
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Figure 16. Unclamped inductive waveform



AM01472v1

Figure 17. Switching time waveform



AM01473v1

4 Package mechanical data

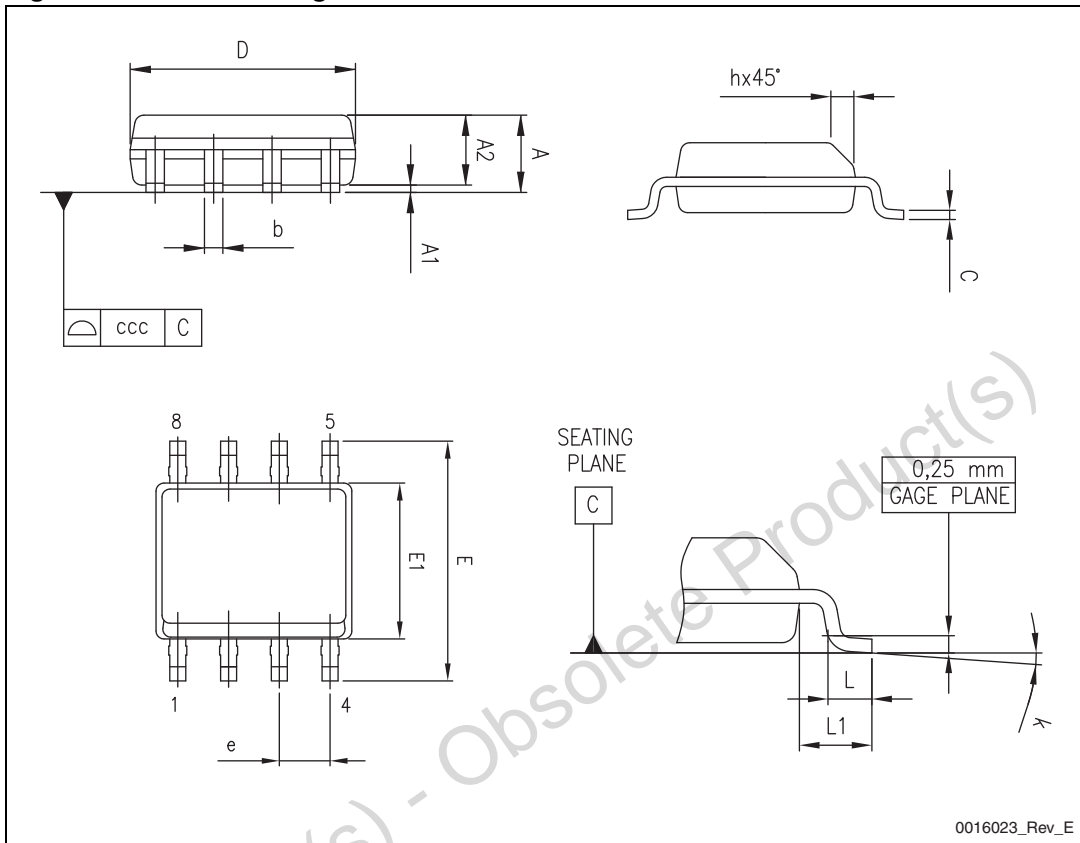
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Table 8. SO-8 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A			1.75
A1	0.10		0.25
A2	1.25		
b	0.28		0.48
c	0.17		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
k	0°		8°
ccc			0.10

Figure 18. SO-8 drawing



5 Revision history

Table 9. Document revision history

Date	Revision	Changes
09-Sep-2004	6	Complete version
17-Aug-2006	7	New template, no content change
31-Jan-2007	8	Typo mistake on Table 2 .
08-May-2007	9	Mistake on Table 7
14-Mar-2012	10	Table 1: Device summary has been corrected. Minor text changes.

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